#### Supplier Name: Contact Info: Form/Declaration Type: Created on

## Texas Instruments Inc. (DUNS# 00-732-1904) ti.com/support Distribute - RoHS and IEC 62474 DB

06/05/2022

# Details for "OPA551FA/500"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
OPA551FA/500	SN	Level-2-260C-1 YEAR	Ext-Mfg	KTW   7	10.1x8.9x4.5	1573.6

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information** 

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

## **Component Information**

				Homogeneous Material Level		Component Level			
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm		
Bond Wire									
Not Categorized	Proprietary Materials		0.000059	0.007309	73	0.000004	0		
Precious Metals	Gold	7440-57-5	0.80713	99.992691	999927	0.051293	513		
Sub-Total			0.807189	100	1000000	0.051297	513		
Die Attach Adhesive									
Precious Metals	Silver	7440-22-4	1.487346	87.000005	870000	0.094521	945		
Thermoplastics	Epoxy	85954-11-6	0.222247	12.999995	130000	0.014124	141		
Sub-Total			1.709593	100	1000000	0.108644	1086		
Lead Frame									
Copper and Its Alloys	Copper	7440-50-8	899.1	99.9	999000	57.137718	571377		
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.9	0.1	1000	0.057195	572		
Sub-Total			900	100	1000000	57.194913	571949		
Lead Frame Plating									
Other Nonferrous Metals and Alloys	Tin	7440-31-5	8.98	100	1000000	0.570678	5707		
Sub-Total			8.98	100	1000000	0.570678	5707		
Mold Compound									
Other Inorganic Materials	Fused Silica	60676-86-0	556.710953	84.81	848100	35.378927	353789		
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	34.133911	5.2	52000	2.169207	21692		
Other Plastics and Rubber	Carbon Black	1333-86-4	1.378485	0.21	2100	0.087603	876		
Thermoplastics	Epoxy	85954-11-6	64.198009	9.78	97800	4.079777	40798		
Sub-Total			656.421358	100	1000000	41.715514	417155		
Semiconductor Device									
Ceramics / Glass	Doped Silicon	7440-21-3	5.648377	100	1000000	0.358954	3590		
Sub-Total			5.648377	100	1000000	0.358954	3590		
Total			1573.566517			100	1000000		

### Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

The ppm activation of the transmission of the

See Glossary of Terms for more details.

## Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology For an explanation of the methods used to determine material weights, See Product Content Methodology

## Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

#### Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

## Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/05/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.